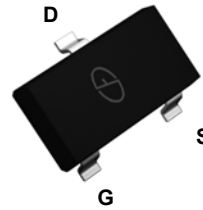
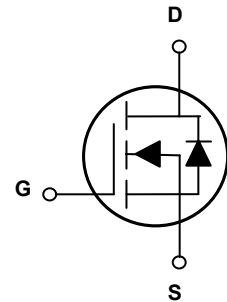


### Main Product Characteristics

$V_{(BR)DSS}$	30V
$R_{DS(ON)}$	24mΩ
$I_D$	6.5A



SOT-23



Schematic Diagram

### Features and Benefits

- Advanced MOSFET process technology
- Ideal for MB/VGA/Core and load switch
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



### Description

The SSF3912S utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

### Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current – Continuous ( $T_C=25^\circ\text{C}$ )	$I_D$	6.5	A
Drain Current – Continuous ( $T_C=100^\circ\text{C}$ )		4.1	A
Drain Current – Pulsed <sup>1</sup>	$I_{DM}$	26	A
Single Pulse Avalanche Energy <sup>2</sup>	$E_{AS}$	32	mJ
Single Pulse Avalanche Current <sup>2</sup>	$I_{AS}$	8	A
Power Dissipation ( $T_C=25^\circ\text{C}$ )	$P_D$	1.56	W
Power Dissipation – Derate above $25^\circ\text{C}$	$P_D$	0.012	W/ $^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55 to +150	$^\circ\text{C}$
Operating Junction Temperature Range	$T_J$	-55 to +150	$^\circ\text{C}$

### Thermal Characteristics

Parameter	Symbol	Typ.	Max.	Unit
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	---	80	$^\circ\text{C}/\text{W}$

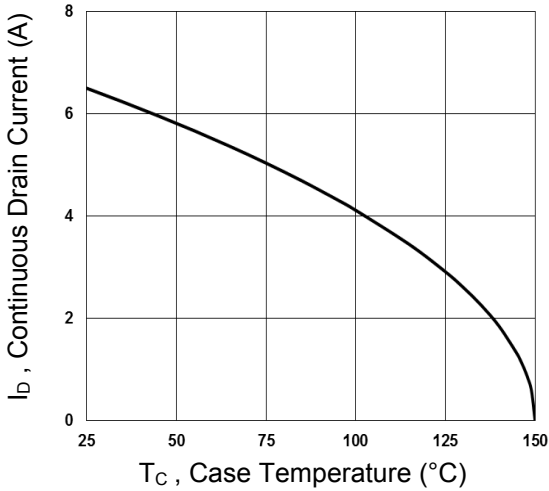
**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	30	---	---	V
$BV_{DSS}$ Temperature Coefficient	$\Delta BV_{DSS}/\Delta T_J$	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.04	---	$V/^\circ\text{C}$
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=30V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	1	$\mu A$
		$V_{DS}=24V, V_{GS}=0V, T_J=125^\circ\text{C}$	---	---	10	$\mu A$
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 100$	nA
<b>On Characteristics</b>						
Static Drain-Source On-Resistance <sup>3</sup>	$R_{DS(ON)}$	$V_{GS}=10V, I_D=6A$	---	20	24	$m\Omega$
		$V_{GS}=4.5V, I_D=4A$	---	27	34	$m\Omega$
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	1.2	1.6	2.5	V
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}$		---	-4	---	$mV/^\circ\text{C}$
Forward Transconductance	$g_{fs}$	$V_{DS}=10V, I_D=4A$	---	6.5	---	S
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge <sup>3, 4</sup>	$Q_g$	$V_{DS}=15V, V_{GS}=4.5V, I_D=6A$	---	4.1	8	nC
Gate-Source Charge <sup>3, 4</sup>	$Q_{gs}$		---	1	2	
Gate-Drain Charge <sup>3, 4</sup>	$Q_{gd}$		---	2.1	4	
Turn-On Delay Time <sup>3, 4</sup>	$T_{d(on)}$	$V_{DD}=15V, V_{GS}=10V, R_G=6\Omega, I_D=1A$	---	2.8	5	nS
Rise Time <sup>3, 4</sup>	$T_r$		---	7.2	14	
Turn-Off Delay Time <sup>3, 4</sup>	$T_{d(off)}$		---	15.8	30	
Fall Time <sup>3, 4</sup>	$T_f$		---	4.6	9	
Input Capacitance	$C_{iss}$	$V_{DS}=25V, V_{GS}=0V, F=1\text{MHz}$	---	345	500	pF
Output Capacitance	$C_{oss}$		---	55	80	
Reverse Transfer Capacitance	$C_{rss}$		---	32	45	
Gate Resistance	$R_g$	$V_{GS}=0V, V_{DS}=0V, F=1\text{MHz}$	---	3.2	6.4	$\Omega$
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Continuous Source Current	$I_S$	$V_G=V_D=0V, \text{Force Current}$	---	---	6.5	A
Pulsed Source Current <sup>3</sup>	$I_{SM}$		---	---	26	A
Diode Forward Voltage <sup>3</sup>	$V_{SD}$	$V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$	---	---	1	V
Reverse Recovery Time	$t_{rr}$	$V_{GS}=0V, I_S=1A, di/dt=100A/\mu S, T_J=25^\circ\text{C}$	---	---	---	nS
Reverse Recovery Charge	$Q_{rr}$		---	---	---	nC

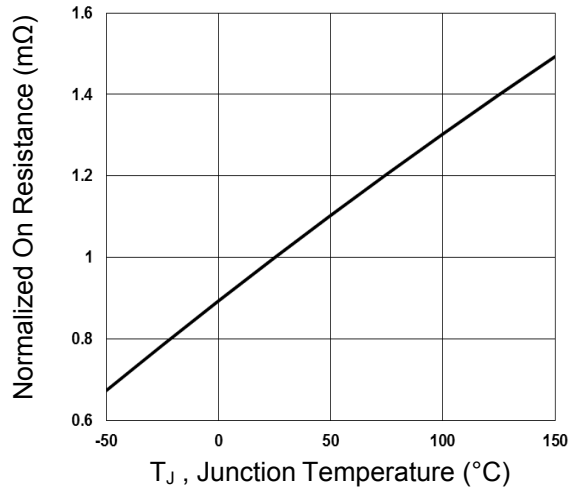
Note:

1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=25V, V_{GS}=10V, L=1\text{mH}, I_{AS}=8A, R_G=25\Omega$ , Starting  $T_J=25^\circ\text{C}$ .
3. The data tested by pulsed, pulse width  $\leq 300\mu S$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.

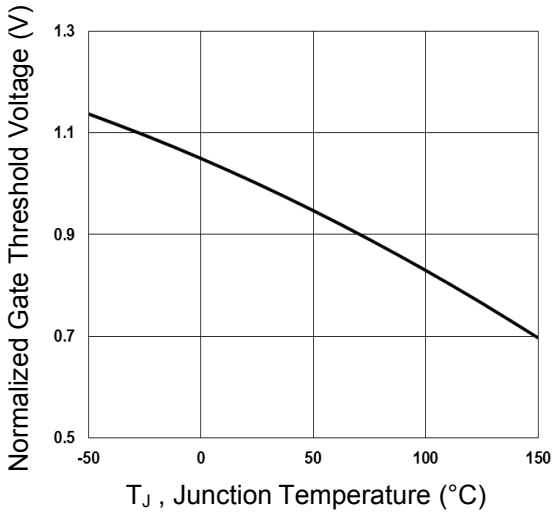
**Typical Electrical and Thermal Characteristics**



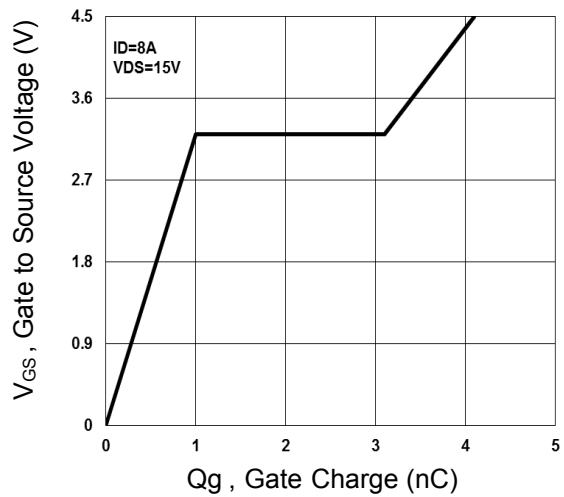
**Fig.1 Continuous Drain Current vs.  $T_C$**



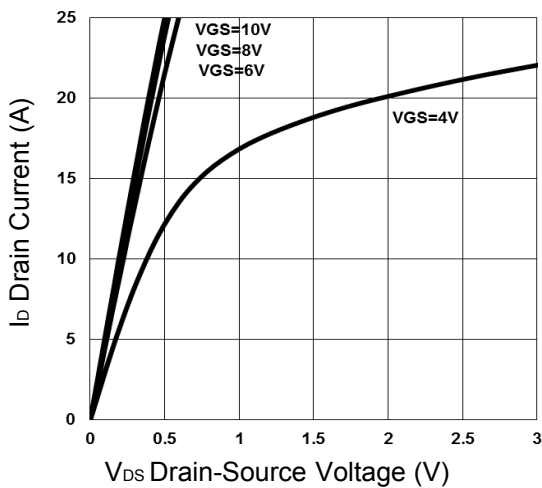
**Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_J$**



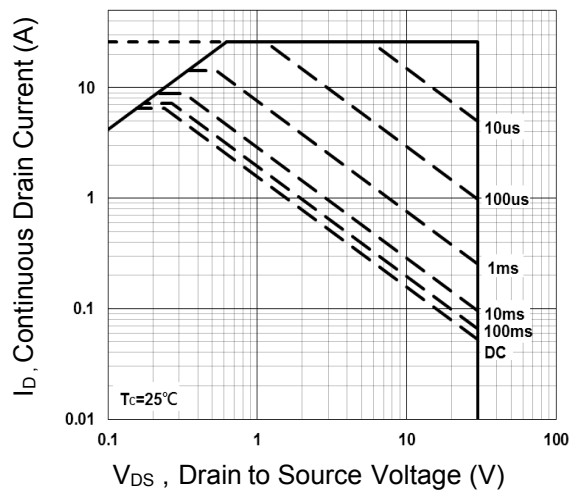
**Fig.3 Normalized  $V_{th}$  vs.  $T_J$**



**Fig.4 Gate Charge Waveform**

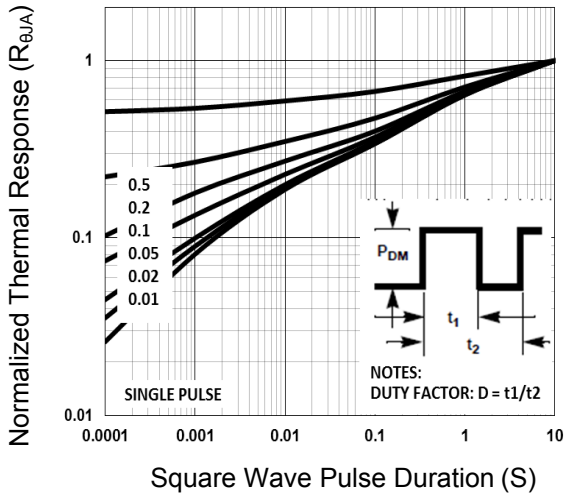


**Fig.5 On Region Characteristics**

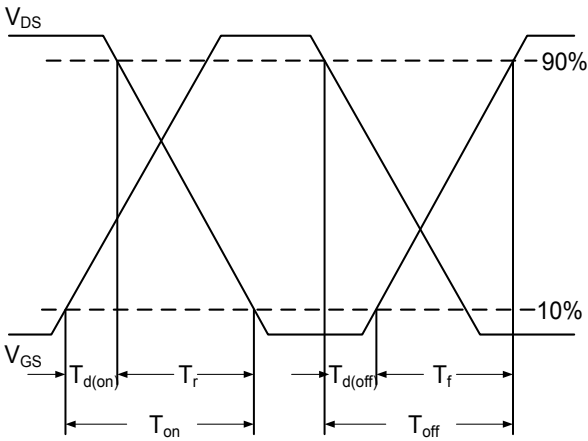


**Fig.6 Maximum Safe Operation Area**

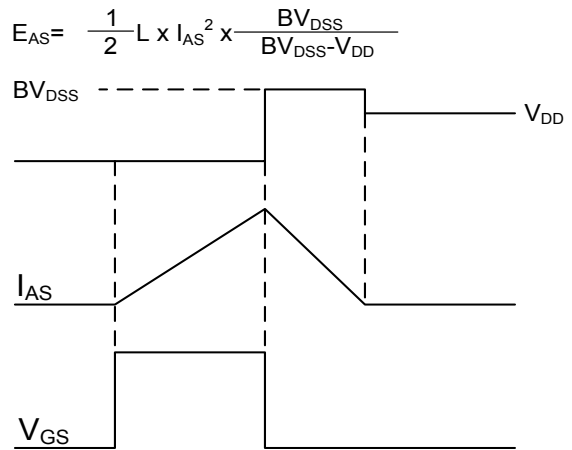
**Typical Electrical and Thermal Characteristics**



**Fig.7 Normalized Transient Response**



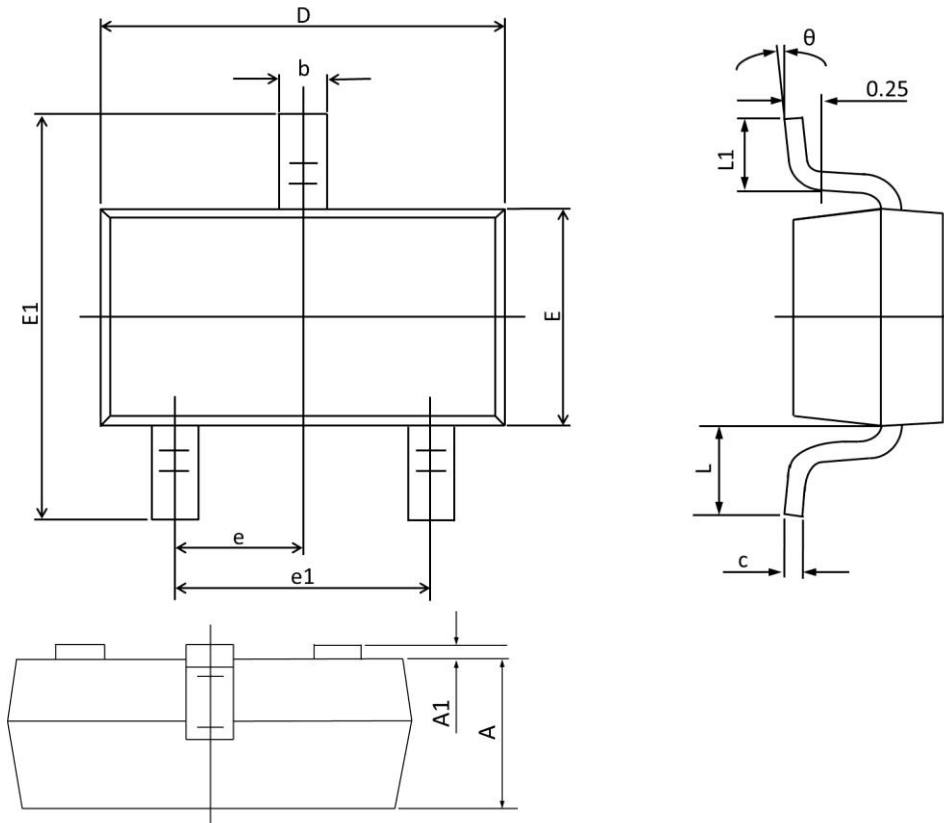
**Fig.8 Switching Time Waveform**



**Fig.9  $E_{AS}$  Waveform**

**Package Outline Dimensions**

**SOT-23**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.000	0.035	0.039
A1	0.000	0.100	0.000	0.004
b	0.300	0.500	0.012	0.020
c	0.090	0.110	0.003	0.004
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020
θ	1°	7°	1°	7°